

HSFPAR0 series application note

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Application note HSFPAR0 series

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History of revision

Rev.	Date	Note
1.0	Apr/4/2017	First edition
1.1	Jun/26/2017	Add P8
1.2	Oct/2/2017	Revised P9
1.3	Jul/9/2018	Revised P5, P7, P8, P9
2.0	Dec/21/2018	Update design guide
2.1	Apr/2/2019	Company name revision.
2.2	Apr/8/2019	Fixed typo P5, P6, P7



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1. Overview

本製品は、シリコンダイアフラム上にピエゾ抵抗が形成されており、荷重が加わるとダイアフラムが撓むことでピエゾ抵抗に応力が発生し、抵抗率が変化するピエゾ抵抗効果を利用した荷重センサ。

• This product is a force sensor using effect of piezo resistive bridge circuit formed on silicon diaphragm.

• Piezo resistance is changed according to strain by applying force to the diaphragm.

2. Features

・小型低背です。

PKGサイズが小さくスペースを取らないため、様々な製品デザインに対応出来ます。

・感度が高く、直線性に優れます。

0.01Nレベルの小さな応力から検出可能です。

・信頼性に優れます。

100万回の荷重試験後で、特性の変化は有りません。

·Small Footprint and Low Profile

User design flexibility by small package.

•High Sensitivity and Good Linearity.

Precisely detect micro force less than 0.01 N.

·High Durability.

No characteristics change after 1 million cycles.

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3. Design guide

3-1 Precautions

- Please don't apply the static force and the impact force of max load rating or more to this sensor.
- Must be pressed with a metal plate. Recommendation: SUS440C,t=0.2mm
- Characteristic abnormality may occur when using resin type like plastic.



*1 :Note) Please refer to the data sheet for the max load rating of the force sensor.

• Please don't apply force at an angle to the sensor.



•The dust such as sand must not enter.

• Something that corrode solder must not enter.











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4. Legal disclaimer

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5. Notes concerning patent

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